ABSTRACT OF THE DISCLOSURE

A wire loop comprises a wire connecting a first bonding point and a second bonding point therethrough, wherein the wire has a crushed part formed therein by crushing the part of the wire and a top of a ball bonded to the first bonding point with a capillary. The wire loop is formed by a wire bonding method which includes: bonding the wire to the first bonding point; moving the capillary horizontally and vertically while carrying out loop control; bonding the wire to the vicinity of the top of the ball bonded to the first bonding point; and thereafter, moving the capillary horizontally and vertically to the second bonding point while delivering the wire and carrying out loop control, and then bonding the wire to the second bonding point.